

## STN セミナー

# WPI 公報レベルの活用



2015年2月

## 本日の内容

- ・ WPI ファイルのレコード構成
- ・ 公報レベルの活用
  - 発明者, 出願人
  - 国際特許分類 (IPC)
  - 著者抄録, クレーム
    - ・ 収録状況
    - ・ 検索フィールド
    - ・ テキスト中の数値検索

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化学情報協会



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## WPI ファイルの概要

- ・ 製作者 : トムソン・ロイター
- ・ 収録範囲 : 世界中の特許 (1963 年~)  
全技術分野
- ・ 特長 : トムソン・ロイター作成の詳細な  
英文抄録, 索引が収録されている

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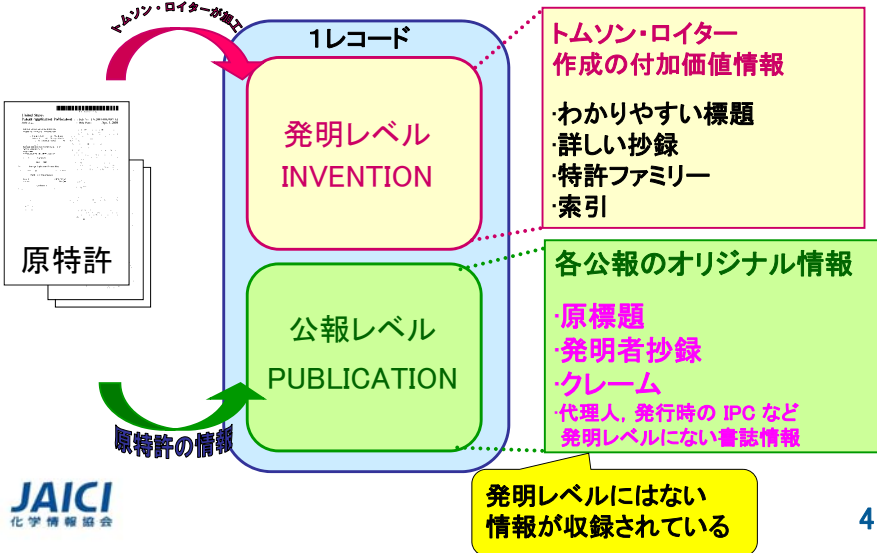
## WPI ファイルのレコード構成

- ・ 1 レコード = 1 発明 = 1 特許ファミリー
- ・ 1 レコード = 発明レベル (INVENTION)  
+  
公報レベル (PUBLICATION)

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# 発明レベルと公報レベル



# レコード例 (発明レベル)

AN 2014-M23307 [201444] WPINDEX Full-text  
 ED 20140714  
 TI Epoxy resin, useful for encapsulating a semiconductor device, composition comprises an epoxy resin, a curing agent, a curing accelerator, a coupling agent, which comprises an alkylsilane compound and an inorganic filler  
 DC A21: A85; E11; L03: U11  
 IN BAE K C; BAE K  
 PA (BAEK-1) BAE K C; (CHLL-C) CHEIL IND INC  
 CPC 3  
 PI US 20140179832 A1 20140626 (201444)\* EN 10[1]  
 KR 2014082521 A 20140702 (201445) KO  
 CN 103897342 A 20140702 (201460) ZH  
 ADT US 20140179832 A1 US 2013-71781 20131105; KR 2014082521 A KR 2012-152612 20121224; CN 103897342 A CN 2013-10513881 20131025  
 PRAI KR 2012-152612 20121224  
 IPCI C08K0003-00 [I.A]; C08K0005-5415 [I.A]; C08L0003-29 [I.A]; H01L0023-29 [I.A]; C08K0013-04 [I.A]; C08K0003-04 [I.A]; C08K0003-22 [I.A]; C08K0005-54 [I.A]; C08K0005-5435 [I.A]; C08K0005-548 [I.A]; C08K0007-18 [I.A]  
 CPC H01L0023-295  
 NCL NCLM 523/466.000  
 AB US 20140179832 A1 UPAB: 20140919  
 NOVELTY - Epoxy resin composition comprises an epoxy resin, a curing agent, a curing accelerator, a coupling agent, which comprises an alkylsilane compound (I) and an inorganic filler.  
 DETAILED DESCRIPTION - Epoxy resin composition comprises an epoxy resin, a curing agent, a curing accelerator, a coupling agent, which comprises an alkylsilane compound of formula (I) and an inorganic filler.  
 R1-R3 = 1-4C-alkyl, preferably GH3;  
 R = 6-31C-alkyl; and  
 n = 1-5.  
 USE - The epoxy resin composition is useful for encapsulating a semiconductor device (claimed).  
 ADVANTAGE - The epoxy resin composition: protects the semiconductor devices from an external environment such as corrosion and exhibits improved moisture resistance, excellent flexural strength, package reliability, adhesiveness, moldability, crack resistance, tensile property, low thermal expansion and improved mechanical elasticity.  
 TECH ORGANIC CHEMISTRY - Preferred Components: (I) has a viscosity of 40-60 mPa, as measured at 25 degrees C in 50% methanol solution; a specific gravity of 0.7-1.8; and a refractive index of 0.85-1.25. The amount of (I) in the composition is 0.01-15 wt.% and the coupling agent is 20-100 wt.%. The coupling agent further comprises an epoxy silane, an aminosilane, a  
**抄録**

# トムソン・ライター作成情報を収録

IT UPI1 2014  
 184613-CL 184613-USE: 1207-47201-CL 1207-47201-USE: 1469-EX 1469-USE:  
 107016-EX 107016-USE: 129340-EX 129340-USE: 231-EX 231-USE  
 FS CPI: EPI  
 MC CPI: A05-A01E2; A08-001; A08-M01; A12-E04; A12-E07C; E05-E02D;  
 E05-G02; E31-M; E31-P03; L04-C20A; L04-E  
 EPI: U11-A07; U11-E02A  
 PLE UPA 20140714  
 [1.1] 2004 P0463 P0442 P0444 D01 D18 F30;  
 [1.2] 2004 G1105 G1092 D01 D19 D18 D31 D50 D76 D86 F31 F30 DCN: R00868  
 DCR: 181; P0497 P0464 P0228 P0282 M2175 D01 D18; H0011-R;  
 [1.3] 2004 P0463 P0442 P0444 D01 D18 F30; M999 M2175;  
 [1.4] 2004 D19 D18 D32 D76 D50; P0464-R D01 D22 D42 F47;  
 [1.5] 2004 P0464-R D01 D22 D42 F47;  
 [1.6] 2004 B9999 B4717 B4706 B4568; B9999 B4148 B4091 B3383 B3747;  
 B9999 B5301 B5298 B5276; B9999 B3623 B3554; B9999 B4711 B4091  
 B3838 B3747; B9999 B5538 B5505; B9999 B3747-R; B9999 B3930-R  
 B3838 B3747; Q9999 Q7476 Q7330; Q9999 Q7523; N004; M001; K9449;  
 CMC UPB 20140714  
 DRN: 1694-U 1527-U 1408-U  
 DCR: 107016-U 129340-U 231-U  
 M3 \*01\* M423 M424 M782 0454 R038 M905  
 DCN: RA0019-K RA0019-M  
 DCR: 184613-K 184613-M  
 M3 \*02\* B414 B713 B720 B741 B742 B744 B740 B780 B831 B832 B833 M210 M211  
 M212 M213 M214 M215 M216 M220 M221 M222 M223 M224 M225 M226 M231  
 M232 M233 M250 M272 M281 M282 M283 M280 M411 M424 M510 M520 M530  
 M540 M620 M782 0454 R038 M905 M904  
 MCN: 1207-47201-K 1207-47201-M  
 M3 \*03\* B414 B713 B720 B741 B831 M210 M211 M250 M272 M281 M283 M320 M411  
 M424 M510 M520 M530 M540 M620 M782 0454 R038 M905 M904  
 DCN: R08655-K R08655-M  
 DCR: 1469-K 1469-M  
 M3 \*04\* B114 B702 B720 B831 C108 C800 C802 C803 C804 C805 C807 M411 M424  
 M782 0454 0606 R038; M905 M904  
 DCN: R01524-K R01524-M  
 DCR: 107016-K 107016-M  
 M3 \*05\* A351 A940 C108 C550 C730 C801 C802 C803 C804 C805 C807 M411 M424  
 M782 0454 0606 R038; M905 M904 M910  
 DCN: R01527-K R01527-M  
 DCR: 129340-K 129340-M

**索引**

# レコード例 (公報レベル)

**Member (0001)**

特許情報  
 標題 **TIEN EPOXY RESIN COMPOSITION FOR ENCAPSULATING A SEMICONDUCTOR DEVICE ENCAPSULATED USING THE SAME** **TIEN : 原標題**  
 発明者 **INO: BAE, Kyoung Chul** **INO : 発明者 (オリジナル)**  
 出願人 **INA: Uiwang-si, KR** **INA : 発明者住所**  
 出願人 **PA (BAEK-1) BAE K C**  
 出願人 **PAO: BAE, Kyoung Chul** **PAO : 出願人 (オリジナル)**  
 出願人 **PAA: Uiwang-si, KR** **PAA : 出願人住所**  
 出願情報 **ADT US 20140179832 A1 US 2013-71781 20131105**  
 出願情報 **APTS 2013US-000071781 20131105**  
 優先権情報 **PRAI KR 2012-152612 20121224**  
 優先権情報 **PRTS 2012KR-000152612 20121224**  
 IPC, 現行 **IPCI Current: H01L0023-29 [I,A]** **IPC Original : 発行時の IPC**  
 IPC, 発行時 **Original: H01L0023-29 [I,A]**  
 CPC, 現行 **CPC Current: H01L0023-295**  
 CPC, 発行時 **Original: H01L0023-295**  
 NCL **NCL NCLM 523/466.000**  
**ABEN : 発明者抄録 (英語)**  
**CLMEN : クレーム (英語)**

**Member (0002)**

**PI KR 2014082521** A 20140702 (201445) KO  
 TIEN EPOXY RESIN COMPOSITION FOR ENCAPSULATING SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE ENCAPSULATED BY USING THE SAME  
 IN BAE K C  
 PA (CHLL-C) CHEIL IND INC  
 PAA: KR  
 ADT KR 2014082521 A KR 2012KR-000152612 20121224  
 IPCI Current: C08K0003-00 H01L0023-29 [I,A]  
 Original: C08K0003-00 H01L0023-29 [I,A]  
 ABEN The epoxy resin composition provides the present invention, the hardening acceleration, and the coupling agent.  
 CLMEN [CLAIM 1] The epoxy resin composition, comprising: an epoxy resin, a curing accelerator, the coupling agent, and an inorganic filler, wherein the coupling agent is represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl group, R4 is a C6 to C31 alkyl group, and n ranges from about 1 to 5 on average.  
 [CLAIM 9] The semiconductor device comprising the epoxy resin composition described in any one of claims 1 to 8.

**Member (0003)**

**PI CN 103897342** A 20140702 (201460) ZH  
 TIEN Encapsulating epoxy resin composition for a semiconductor device and use the package of semiconductor device  
 IN BAE K  
 PA (CHLL-C) CHEIL IND INC  
 PAA: KR  
 ADT KR 2014082521 A KR 2012KR-000152612 20121224  
 IPCI Current: C08K0003-00 H01L0023-29 [I,A]  
 Original: C08K0003-00 H01L0023-29 [I,A]  
 ABEN The invention provide the encapsulating epoxy resin composition for a semiconductor device and use the package of semiconductor device, said composition comprises the epoxy resin, curing agent, curing accelerator, coupling agent and inorganic filler, wherein the coupling agent is represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl radical, and n ranges from about 1 to 5 on average.  
 CLMEN [CLAIM 1] a one encapsulating epoxy resin composition for a semiconductor device, comprising: an epoxy resin, a curing agent, a curing accelerator, a coupling agent, and an inorganic filler, wherein the coupling agent comprises by represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl radical, and n ranges from about 1 to 5 on average.  
 [CLAIM 9] a use according to any one of claims 1 to 8 in said epoxy resin composition for a semiconductor device.

**公報ごとに情報がまとめられている**

**公報レベルの収録内容**

- ・原標題
- ・発明者 (フルネーム), 発明者住所
- ・出願人, 出願人住所
- ・代理人, 代理人住所
- ・発行時の特許分類
- ・発明者抄録
- ・クレーム (メインクレーム 或 全クレーム)

\* 国、特許種別、年代によって収録内容が異なる

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# レコード例 (公報レベル)

**Member (0001)**

特許情報  
 標題 **TIEN EPOXY RESIN COMPOSITION FOR ENCAPSULATING A SEMICONDUCTOR DEVICE ENCAPSULATED USING THE SAME** **TIEN : 原標題**  
 発明者 **INO: BAE, Kyoung Chul** **INO : 発明者 (オリジナル)**  
 出願人 **INA: Uiwang-si, KR** **INA : 発明者住所**  
 出願人 **PA (BAEK-1) BAE K C**  
 出願人 **PAO: BAE, Kyoung Chul** **PAO : 出願人 (オリジナル)**  
 出願人 **PAA: Uiwang-si, KR** **PAA : 出願人住所**  
 出願情報 **ADT US 20140179832 A1 US 2013-71781 20131105**  
 出願情報 **APTS 2013US-000071781 20131105**  
 優先権情報 **PRAI KR 2012-152612 20121224**  
 優先権情報 **PRTS 2012KR-000152612 20121224**  
 IPC, 現行 **IPCI Current: H01L0023-29 [I,A]** **IPC Original : 発行時の IPC**  
 IPC, 発行時 **Original: H01L0023-29 [I,A]**  
 CPC, 現行 **CPC Current: H01L0023-295**  
 CPC, 発行時 **Original: H01L0023-295**  
 NCL **NCL NCLM 523/466.000**  
**ABEN : 発明者抄録 (英語)**  
**CLMEN : クレーム (英語)**

**Member (0002)**

**PI KR 2014082521** A 20140702 (201445) KO  
 TIEN EPOXY RESIN COMPOSITION FOR ENCAPSULATING SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE ENCAPSULATED BY USING THE SAME  
 IN BAE K C  
 PA (CHLL-C) CHEIL IND INC  
 PAA: KR  
 ADT KR 2014082521 A KR 2012KR-000152612 20121224  
 IPCI Current: C08K0003-00 H01L0023-29 [I,A]  
 Original: C08K0003-00 H01L0023-29 [I,A]  
 ABEN The epoxy resin composition provides the present invention, the hardening acceleration, and the coupling agent.  
 CLMEN [CLAIM 1] The epoxy resin composition, comprising: an epoxy resin, a curing accelerator, the coupling agent, and an inorganic filler, wherein the coupling agent is represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl group, R4 is a C6 to C31 alkyl group, and n ranges from about 1 to 5 on average.  
 [CLAIM 9] The semiconductor device comprising the epoxy resin composition described in any one of claims 1 to 8.

**Member (0003)**

**PI CN 103897342** A 20140702 (201460) ZH  
 TIEN Encapsulating epoxy resin composition for a semiconductor device and use the package of semiconductor device  
 IN BAE K  
 PA (CHLL-C) CHEIL IND INC  
 PAA: KR  
 ADT KR 2014082521 A KR 2012KR-000152612 20121224  
 IPCI Current: C08K0003-00 H01L0023-29 [I,A]  
 Original: C08K0003-00 H01L0023-29 [I,A]  
 ABEN The invention provide the encapsulating epoxy resin composition for a semiconductor device and use the package of semiconductor device, said composition comprises the epoxy resin, curing agent, curing accelerator, coupling agent and inorganic filler, wherein the coupling agent is represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl radical, and n ranges from about 1 to 5 on average.  
 CLMEN [CLAIM 1] a one encapsulating epoxy resin composition for a semiconductor device, comprising: an epoxy resin, a curing agent, a curing accelerator, a coupling agent, and an inorganic filler, wherein the coupling agent comprises by represented by the following formula 1:  
 [Formula 1]  $R_1R_2R_3C_1C_2C_3C_4$ , wherein R1, R2 and R3 are each independently a C1 to C4 alkyl radical, and n ranges from about 1 to 5 on average.  
 [CLAIM 9] a use according to any one of claims 1 to 8 in said epoxy resin composition for a semiconductor device.

**公報ごとに情報がまとめられている**

**公報レベルの収録内容**

- ・原標題
- ・発明者 (フルネーム), 発明者住所
- ・出願人, 出願人住所
- ・代理人, 代理人住所
- ・発行時の特許分類
- ・発明者抄録
- ・クレーム (メインクレーム 或 全クレーム)

\* 国、特許種別、年代によって収録内容が異なる

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## 公報レベルの活用

- ① 発明者, 出願人
- ② 国際特許分類 (IPC)
- ③ 著者抄録, クレーム

## 発明者情報

### 発明レベル

IN WHITTINGHAM W G

発明者 (/IN)

\* 発明レベルの発明者名は  
ファーストネームとミドルネームは  
イニシャルのみ

### 公報レベル

IN WHITTINGHAM W G  
INO: WHITTINGHAM, William Guy  
INA: Syngenta Limited, Jealotts Hill ...

発明者(オリジナル) (/INO)

\* 公報レベルの発明者名は公報の記載通りなので  
フルネームが収録されていることが多い

## 出願人関連情報

- 公報レベルには、出願人住所、発明者住所、代理人など、  
発明レベルには収録されていない情報がある

### 発明レベル

IN WHITTINGHAM W G (出願人コード (/PACO))  
PA (SYGN-C) SYNGENTA LTD (出願人 (/PA))

### 公報レベル

AG SYNGENTA INTERNATIONAL AG (代理人 (/AG.T))  
AGA: Intellectual Property, WRO 1008-Z1-26,  
:  
IN WHITTINGHAM W G (発明者住所 (/INA))  
INO: WHITTINGHAM, William Guy  
INA: Syngenta Limited, Jealotts Hill ...  
PA (SYGN-C) SYNGENTA LTD (公報レベルの出願人  
情報 (/PA.T))  
PAO: SYNGENTA LIMITED  
PAA: European Regional Centre, Priestley Road ...  
:

## 出願人検索

- 公報レベルの出願人関連情報も検索対象に  
含めるとより網羅的な検索になる

=> S SYNGENTA/PA OR SYGN/PACO ← 発明レベルの出願人情報  
L1 2805 SYNGENTA/PA OR SYGN/PACO

=> S SYNGENTA/PA. T, AG. T, INA ← 公報レベルの出願人関連情報  
L2 2586 SYNGENTA/PA. T, AG. T, INA

=> S L1 OR L2  
L3 2849 L1 OR L2

AN 2009-M56891 [200955] WPINDEX [Full-text](#)  
 TI New nucleic acid encoding plastid transit peptide from Glaucocystophyte, useful for stably expressing a heterologous polypeptide in a plant and for producing transgenic plants with desired traits  
 DC C06; D16; P13  
 IN HIPSKIND J; MILES S; WARREN G W

PA (HIPS-I) HIPSKIND J; (MILE-I) MILES S; (WARR-I) WARREN G W  
 CYC 1  
 PI US 20090205075 A1 20090813 (200955)\* EN 19[0]

出願人フィールドには会社名なし

Member (0001)  
 PI US 20090205075 A1 20090813 (200955)\* EN 19[0]  
 TIEN USE OF PLASTID TRANSIT PEPTIDES DERIVED FROM GLAUCOCYSTOPHYTES

AG SYNGENTA BIOTECHNOLOGY, INC.; PATENT DEPARTMENT  
 AGA: 3054 CORNWALLIS ROAD, P.O. BOX 12257, RESEARCH TRIANGLE PARK, NC, US

IN HIPSKIND J  
 INO: Hipkind, John  
 INA: Durham, NC, US  
 Residence: US

代理人でヒット!

PA (MILE-I) MILES S  
 PAO: Miles, Stacy  
 PAA: Durham, NC, US  
 Residence: US

## IPC の収録

発明レベルには、各ファミリー特許由来の現行の IPC がまとめて収録されている

### 発明レベル IPC.TAB 表示形式

IPC	CODE	VERSION	POS	INV	LEVEL	CC	ASSIGNMENT DATE	STAT
IPC1	C08K0003-08	(200601)	L	I	Advanced			0
IPCR	B32B0017-10	(200601)		I	Advanced			R
IPCR	C08K0005-521	(200601)		I	Advanced			R

### 公報レベル IPC.TAB.M 表示形式

Member (0001)

Current ← 現行の IPC

IPCR	B32B0017-10	(200601)		I	Advanced EP Machine		20060722	R
IPCR	C08K0005-521	(200601)		I	Advanced EP Machine		20051008	R

Original ← 発行時の IPC

ICM	C08L0029-14							
ICS	B32B0027-00							

Member (0002)

IPC	CODE	VERSION	POS	INV	LEVEL	CC	ASSIGNMENT DATE	STAT
Current								
IPC1	C08K0003-08	(200601)	L	I	Advanced CN Human		20060913	0
Original								

公報レベルには、各公報の発行時の IPC および現行の IPC が収録されている

## IPC の検索

- /IPC で、発明レベル、公報レベルのすべての IPC 関連フィールドを対象として検索できる

IPC8 のフィールド			/IPC
IPC1 (発行時)		- *1	
IPCR (再分類)		- *2	
旧版 (1-7 版) のフィールド			
ICM (主分類)	/IC *3	/ICM *3	
ICS (副分類)	/IC *3	/ICS *3	
ICA (追加情報)		/ICA *3	
ICI (インデキシングコード)		/ICI *3	

\*1 => S ###/IPC (S) O/IPC.KW で発行時の IPC に限定できる  
 \*2 => S ###/IPC (S) R/IPC.KW で再分類の IPC に限定できる  
 \*3 発行時の IPC の検索フィールドは、先頭に I をつける <例> /IPC

## 著者抄録, クレームの収録

<例>

Member (0003)  
 PI MX 2014003782 A1 20140930 (201477) ES  
 IN KIKUCHI T  
 KASHIYAMA T  
 KASHIYAMA T  
 PA (HIRS-C) HIRATA CORP  
 ADT MX 2014003782 A1 MX 2014-3782 20140328  
 APTS 2014MX-000003782 20140328  
 PRAI JP 2013-70430 20130328  
 PRIS 2013JP-000070430 20130328  
 IPCI Current: A43D0011-00 [I,A]  
 Original: A43D0011-00 [I,A]

INO なし

抄録やクレームなし

国や特許種別, 年代によって情報量が異なる

Member (0004)  
 PI CN 104070338 A 20141001 (201501) ZH  
 TIEN Assembling device and control method  
 IN KASHIYAMA M  
 INO: KASHIYAMA, MASA  
 INA: JP  
 KIKUCHI T  
 INO: KIKUCHI, TAKAHIRO  
 INA: JP  
 PA (HIRS-C) HIRATA SPINNING LTD  
 PAA: JP  
 ADT CN 104070338 A CN 2014-10120869 20140328  
 APTS 2014CN-010120869 20140328  
 PRAI JP 2013-70430 20130328  
 PRIS 2013JP-000070430 20130328  
 IPCI Current: B23P0019-00 [I,A]  
 Original: B23P0019-00 [I,A]  
 ABEN The invention provide one assembling device and a control method, assembling device having main pallet and the auxiliary pallet relative separated main plate frame,  
 CLMEN [CLAIM 1] a one assembling device with one key for a valve holding base assembly, having the jar head, wherein main pallet, the loading jar  
 [CLAIM 2] According to claim claim 1 of said assembling device, wherein, further having examination device, arranged on the said

INO あり

抄録やクレームあり

## クレームが収録されている特許

発行国/機関	特許種別	収録年	発行国/機関	特許種別	収録年
EP	A, A1, A2, A9, B3	1991-	CH	A1, A2, B1	2010-
	B, B1, B2	1984-	ES	A, A1, A2, A9, B1, B2, B9, T5, U, U9	2010-
DE	A, A1, B3, B4, B9, C1, C2, C9, T5, U, U1, U9	1968-	GN	A	2007.1-(全クレーム)
JP	A, B, B1, B2	DW200824-		U, Y	2007.6-(全クレーム)
GB	A, B	1984-1997		B, C	2011.1-2012.6-(全クレーム)
US	A	1993-	KR	A, B, B1, B2, U, Y1	2008-(全クレーム)
	A1, A2, A9, B1, B2	2001-	MY	A	2010-
	E, H	2009-	VN	B	2010-
RU	A, U1, U8, U9	2010-	TH	A	2010-
CA	A1	2010-	ID	S	2013-
BR	A2, U2, B1	2010-			

\* CN, KR 以外はメインクレームのみ収録

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## クレームの収録状況- 中国



特許種別	発明者抄録	収録率 (%)	クレーム	収録率 (%)	その他
CNA	2007.6 -	99%<	2007.1 - (全クレーム)	99%<	発明者名 (2009.1 -) 標題 (2007.6 -)
CNB CNC	2012.6 -	99%<	2011.1 - (メインクレーム) 2012.6 - (全クレーム)	99%<	標題 (2007.6 -)
CNU CNY	2007.6 -	99%<	2007.6 - (全クレーム)	99%<	標題 (2007.6 -)

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## クレームの収録状況- 韓国



特許種別	発明者抄録	収録率 (%)	クレーム	収録率 (%)	その他
KRA	2008 -	78%	2008 - (全クレーム)	98%	発明者名 (2009.1 -) 標題 (2008 -)
KRB KRB1 KRB2	2008 -	86%	2008 - (全クレーム)	86%	発明者名 (2009.1 -) 標題 (2008 -)
KRU KRY1	2008 -	99%<	2008 - (全クレーム)	99%<	発明者名 (2009.1 -) 標題 (2008 -)

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## クレームの収録状況

- マレーシア, タイ, ベトナム, インドネシア

特許種別	発明者抄録	収録率 (%)	クレーム	収録率 (%)	その他
MYA	2010 -	94%	2010 - (メインクレーム)	86%	標題 (2010 -)
THA	2010 -	32%	2010 - (メインクレーム)	98%	標題 (2010 -)
VNA	2010 -	63%	-	-	標題 (2010 -)
VNB	2010 -	37%	2010 - (メインクレーム)	90%	標題 (2010 -)
IDA	-	-	2012 - (メインクレーム)	26%	標題 (2012 -) 発明者名 (2012 -) 出願人 (2012 -)
IDS	2012 -	93%	2012 - (メインクレーム)	92%	標題 (2012 -)

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タイ, ベトナム, インドネシアについては, 人手翻訳による英語抄録, メインクレームを収録!

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## <参考> その他のアジア諸国

国	特許種別	標題	発明者抄録	発明者名
台湾	TWA TWB1 TWU	2008 -	2009.7 -	2009.7 -
インド	INA (INI1-4, INP1-4)*1 INB	2009 -	2009 - *2	
シンガポール	SGA1 (国内出願)	2013.5 -	2013.5 -	
	SGA1 (PCT 移行)	2006 -	2006 -	
香港	HKA0 HKA1	2011 -		2011 -
	HKA2	2011 -	2011 -	2011 -
フィリピン	PHA PHB PHB1 PHZ	2010 -	2010 -	

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\*1 INI1-4 は国内出願、INP1-4 は国内移行  
\*2 INI1-4, INB のみ

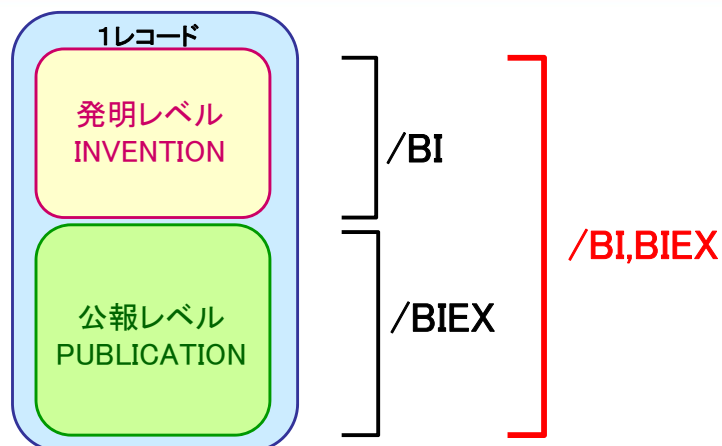
クレームは収録されていないが、  
発明者抄録が収録されている

## 公報レベルのキーワード検索

- 基本索引 (/BI) は発明レベルが検索対象であり、公報レベルの情報は検索されない
- 公報レベルの情報は、**拡張基本索引 (/BIEX)** で検索可能
- 網羅的な検索は、**/BI, BIEX** で

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=> FILE WPINDEX

=> S SUPERCRITICAL WATER ← 基本索引 (/BI) での検索  
L1 1058 S SUPERCRITICAL WATER

=> S SUPERCRITICAL WATER/**BI, BIEX** ← 拡張基本索引を加えた検索  
L2 1390 S SUPERCRITICAL WATER/**BI, BIEX**

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## 公報レベルのキーワード検索

項目	表示フィールド	検索フィールド	拡張基本索引
原標題	TIDE	/TIDE	/BIEX
	TIEN	/TIEN	
	TIES	/TIES	
	TIFR	/TIFR	
発明者抄録	ABDE	/ABDE	
	ABEN	/ABEN	
	ABES	/ABES	
	ABFR	/ABFR	
	ABOL	/ABOL	
クレーム	CLMDE	/CLM	
	CLMEN		
	CLMFR		
	CLMOT		

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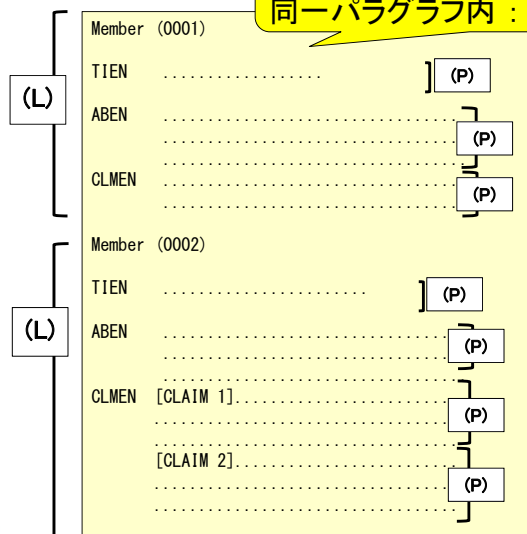
各項目の専用の  
検索フィールドもある

/BIEX でまとめて  
検索できる

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## 近接演算子の範囲

同一公報内 : (L) 近接演算子  
 同一パラグラフ内 : (P) 近接演算子



\* 公報レベルの (S) は (P) と同じ

## <参考> SET SFIELD

- ・ デフォルトの検索フィールドをカスタマイズできる (ファイルごとに設定)

### ・ 入力例

=> FILE WPINDEX

=> SET SFIELD

ENTER DEFAULT SEARCH FIELD OR (BI) : **BI, BIEX**

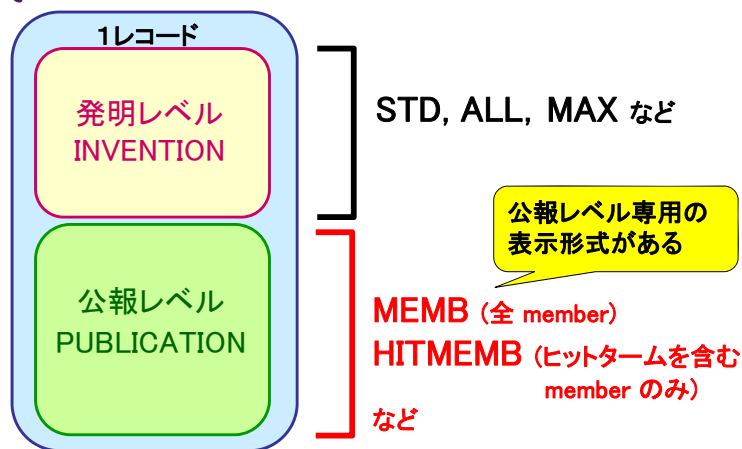
SET COMMAND COMPLETED

=> S FUEL CELL

L1 104802 FUEL CELL /BI, BIEX

毎回 /BI, BIEX  
を入力する手間  
が省ける

## 表示形式



<入力例>

=> D ALL MEMB

=> D MAX HITMEMB

発明レベルの情報と同時に  
出力すれば追加の課金なし

## 検索例

クレームに電気自動車のワイヤレス充電に関する記載のある 2013 年以降の中国特許を調査する

### ポイント

- ・ 中国特許は 2012.6 以降公開・登録特許ともに全クレームが収録されている
- ・ /CLM でクレームに限定できる
- ・ HITMEMB を用いるとヒットした公報の情報のみを表示できる

検索例：クレームに電気自動車のワイヤレス充電に関する記載のある 2013 年以降の中国特許を調査する

=> FILE WPINDEX

← WPINDEX ファイルに入る

=> SET PLU ON;SET ABB ON;SET SPE ON  
SET COMMAND COMPLETED

← 複数形, 略語, 英米綴り違いを自動的に含める設定

=> S (ELECTRIC(W) (VEHICLE OR CAR OR AUTOMOBILE))/CLM  
L1 27397 (ELECTRIC(W) (VEHICLE OR CAR OR AUTOMOBILE))/CLM

/CLM でクレームに限定できる

=> S ((WIRE?(1T)?LESS OR CONTACT?(1T)?LESS OR NON CONTACT OR CONTACT FREE) (1W) (CHARG? OR (POWER OR ENERGY OR ELECTR?) (W) (TRANSFER OR SUPPLY OR TRANSMIT? OR RECEIVE?)))/CLM  
L2 7030 ((WIRE?(1T)?LESS OR CONTACT?(1T)?LESS OR NON CONTACT OR CONTACT FREE) (1W) (CH ARG? OR (POWER OR ENERGY OR ELECTR?) (W) (TRANSFER OR SUPPLY OR TR ANSMIT? OR RECEIVE?)))/CLM

クレーム中の  
キーワードで限定

=> S L1 (P) L2  
L3 205 L1 (P) L2

← 同一クレーム内に限定するには、(P) 演算子を使う

=> S L3 (L) CN/PC (S) 2013<=PY  
L4 118 L3 (L) CN/PC (S) 2013<=PY

← 特定国のクレームに限定する場合は (L) 演算子を使う

=> D ALL HITMEMB 116

← HITMEMB で表示すると、ヒットした公報の情報のみを表示できる  
発明レベル (ALL) の情報と一緒に表示すれば ALL 表示形式の  
料金のみ課金

L4 ANSWER 116 OF 118 WPINDEX COPYRIGHT 2015 THOMSON REUTERS on STN  
AN 2011-P22416 [201177] WPINDEX [Full-text](#)  
TI Resonant-type non-contact electric power feeding system for charging battery of e.g. electric vehicle, sets adjustment device in incommensurate state, when moving portion installation does not receive power from power supply equipment  
DC T01: U24; X12; X16; X21  
IN ICHIKAWA S; NAKAMURA T; SAKODA S; SUZUKI S; TAKADA K; YAMAMOTO Y; SAKOTA S  
PA (TOYX-C) TOYODA AUTOMATIC LOOM WORKS; (TOYT-C) TOYOTA JIDOSHA KK; (TOYX-C) TOYOTA JIDOSHOKKI KK; (TOYT-C) TOYOTA MOTOR CO LTD  
CYC 125  
PI WO 2011142420 A1 20111117 (201177)\* JA 22[1]  
JP 2011244533 A 20111201 (201179) JA 10  
US 20130057082 A1 20130307 (201318) EN  
EP 2571134 A1 20130320 (201321) EN  
CN 102893484 A 20130123 (201330) ZH  
EP 2571134 A8 20130710 (201345) EN  
JP 5307073 B2 20131002 (201364) JA 10  
ADT WO 2011142420 A1 WO 2011-JP60943 20110512; JP 2011244533 A JP 2010-112099 20100514; CN 102893484 A CN 2011-80023623 20110512; EP 2571134 A1 EP 2011-780677 20110512; EP 2571134 A8 EP 2011-780677 20110512; US 20130057082 A1 PCT Application WO 2011-JP60943 20110512; EP 2571134 A1 PCT Application WO 2011-JP60943 20110512; CN 102893484 A PCT Application WO 2011-JP60943 20110512; EP 2571134 A8 PCT Application WO 2011-JP60943 20110512; US 20130057082 A1 US 2012-13697662 20121113; JP 5307073 B2 JP 2010-112099 20100514  
FDT EP 2571134 A1 Based on WO 2011142420 A; CN 102893484 A Based on WO 2011142420 A; EP 2571134 A8 Based on WO 2011142420 A; JP 5307073 B2 Previous Publ JP 2011244533 A  
PRAI JP 2010-112099 20100514  
IPCI B60L0011-18 [I, A]; B60L0005-00 [I, A]; B60M0007-00 [I, A]; H01M0010-46 [I, A]; H02J0017-00 [I, A]; H02J0017-00 [I, A]; H02J0007-00 [I, A]  
CPC B60L0011-182; B60L0011-1833; B60L2210-10; B60L2210-30; B60L2270-40;

発明レベル (ALL) で特許ファミリー情報や  
トムソン・ロイター作成の抄録を確認できる

B60L0003-003; B60L0003-04; H01M0010-46; H02J0005-005; H02J0007-025;  
Y02E0060-12; Y02T0010-7005; Y02T0010-7088; Y02T0010-7216; Y02T0010-7241;  
Y02T0090-12; Y02T0090-122; Y02T0090-125; Y02T0090-127; Y02T0090-14  
EPC B60L0011-18L5; H01M0010-46; H02J0005-00T  
IC0 L60L0270:40; Y02E0060:12; Y02T0010:70B; Y02T0010:70J4; Y02T0090:12D;  
Y02T0090:14  
NCL NCLM 307/104.000  
FCL B60L0011-18 C; B60L0005-00 B; B60M0007-00 X; H01M0010-46; H02J0017-00 B;  
H02J0007-00 301 C; H02J0007-00 301 D  
Main: H02J0007-00 301 D  
Secondary: B60L0011-18 C; B60L0005-00 B; B60M0007-00 X; H01M0010-46;  
H02J0017-00 B; H02J0007-00 301 C  
FTRM 5G503/AA01; 5H125/AA01; 5H030/AA03; 5H030/AA08; 5H125/AC12; 5H125/AC27;  
5H030/AS08; 5G503/BA01; 5H105/BA09; 5G503/BB01; 5H030/BB01; 5H105/BB05;  
5H125/BC22; 5H125/BE02; 5H105/CC07; 5H105/CC19; 5H125/DD02; 5H105/DD10;  
5H030/DD18; 5H125/EE27; 5H125/EE30; 5G503/FA02; 5H125/FF16; 5G503/GB08;  
5H105/GG03; 5H115/PG06; 5H115/PG04; 5H115/PI16; 5H115/PI29; 5H115/PO07;  
5H115/PO09; 5H115/PO16; 5H115/PU01; 5H115/PV02; 5H115/QE12; 5H115/QN03;  
5H115/SE06; 5H115/TI02; 5H115/TI05; 5H115/TI06; 5H115/TO14; 5G503; 5H030;  
5H105; 5H115  
AB WO 2011142420 A1 UPAB: 20111205  
NOVELTY - The system has a vehicle-mounted controller (26) to judge whether power supply equipment (10) feeds electric power to a moving portion installation (20) and to judge whether the moving portion installation receives power from the power supply equipment. The vehicle-mounted controller sets an adjustment device (22) to an incommensurate state, when the moving portion installation refuses to receive power from the power supply equipment based on the judgment information of the vehicle-mounted controller.  
USE - Resonant-type non-contact electric power feeding system for charging battery mounted in vehicle e.g. electric vehicle (claimed).  
ADVANTAGE - The charging operation of the battery mounted in the electric vehicle can be stopped efficiently by setting the adjustment device to the incommensurate state using the controller.  
DESCRIPTION OF DRAWINGS - The drawing shows a circuit block diagram of the resonant-type non-contact electric power feeding system. (Drawing includes non-English language text)  
Power supply equipment (10)  
Primary coil apparatus (13)  
Moving portion installation (20)  
Adjustment device (22)  
Vehicle-mounted controller (26)  
MC EPI: T01-J07D1; U24-H07; X12-C01E; X16-B01; X16-G03; X21-A01F; X21-B01A1; X21-B03

Member (0005)

PI CN 102893484 A 20130123 (201330) ZH

←

TIEN Resonance-type non-contact power supply system  
IN TAKADA K  
INO: TAKADA, KAZUYOSHI  
INA: JP  
SAKODA S  
INO: SAKODA, SHIMPEI  
INA: JP  
YAMAMOTO Y  
INO: YAMAMOTO, YUKIHIRO  
INA: JP  
SUZUKI S

HITMEMB 表示形式はヒットした公報の情報 (この例では Member (0005)) のみを表示できるので、ファミリーが多いときに便利



INO: SUZUKI, SADANORI  
INA: JP  
ICHIKAWA S  
INO: ICHIKAWA, SHINJI  
INA: JP  
NAKAMURA T  
INO: NAKAMURA, TORU  
INA: JP  
PA (TOYT-C) TOYOTA MOTOR CO LTD  
PAA: JP  
ADT CN 102893484 A CN 2011-80023623 20110512; CN 102893484 A PCT Application  
WO 2011-JP60943 20110512  
APTS 2011CN-080023623 20110512; 2011WO-JP0060943 20110512  
FDT CN 102893484 A Based on WO 2011142420 A  
PRAI JP 2010-112099 20100514  
PRTS 2010JP-000112099 20100514  
IPCI Current: B6L0011-18 [I, A]; B6L0005-00 [I, A]; B6M0007-00 [I, A];  
H01M0010-46 [I, A]; H02J0017-00 [I, A]; H02J0007-00 [I, A]  
Original: B6L0011-18 [I, A]; B6L0005-00 [I, A]; B6M0007-00 [I, A];  
H01M0010-46 [I, A]; H02J0017-00 [I, A]; H02J0007-00 [I, A]  
CPC Current: B6L0011-182; B6L0011-1833; B6L2210-10; B6L2210-30;  
B6L2270-40; B6L0003-003; B6L0003-04; H01M0010-46; H02J0005-005;  
H02J0007-025; Y02E0060-12; Y02T0010-7005; Y02T0010-7088; Y02T0010-7216;  
Y02T0010-7241; Y02T0090-12; Y02T0090-122; Y02T0090-125; Y02T0090-127;  
Y02T0090-14  
ABEN Power supply equipment (10) is provided with an AC power supply (11) and  
a primary side resonance coil (13b) which receives a power supply from  
the AC power supply. Power supply device (10) is provided with  
alternating current power supply (11) and receiving the primary side  
resonance coil is power supplied from an AC power source (13b). Portable  
equipment (20) is provided with: a secondary side resonance coil (21b)  
which receives power from the primary side resonance coil; a rectifier  
(23) which rectifies the received power; a charger (24) to which the  
rectified power is supplied; and a power storage device (25) which is  
connected to the charger. The portable equipment (20) is further provided  
with: a matching unit (22) which is provided between the secondary side  
resonance coil (21b) and the rectifier (23); a power supply determination  
unit (26) which determines whether or not power is being supplied to the  
portable equipment (20) from the power supply equipment (10); a power  
reception determination unit (26) which determines whether or not the  
portable equipment is receiving power from the power supply equipment;  
and a control unit (26) which changes, on the basis of the determination  
information from both the power supply determination unit and the power  
reception determination unit, the matching unit to a mismatch state if  
power is being supplied to the portable equipment even though the  
portable equipment is in a state in which the reception of power from the  
power supply equipment should be denied.  
CLMEN [CLAIM 1] A resonance type non-contact power supply system comprising:  
power supply equipment including an AC power source and a primary-side  
resonance coil, which receives power supply from the AC power source; and  
movable body equipment including a secondary-side resonance coil, which  
receives electric power from the primary-side resonance coil, a  
rectifier, which rectifies electric power received by the secondary-side  
resonance coil, a charger, to which electric power rectified by the  
rectifier is supplied, and an electrical storage device, which is  
connected to the charger, wherein the movable body equipment includes: a

matching unit provided between the secondary-side resonance coil and the  
rectifier; a power supply determination unit, which determines whether or  
not electric power is being supplied from the power supply equipment to  
the movable body equipment; a power reception determination unit, which  
determines whether or not the movable body equipment should receive  
electric power from the power supply equipment; and a control unit,  
wherein, on the basis of determination information of the power supply  
determination unit and determination information of the power reception  
determination unit, the control unit brings the matching unit into a  
mismatch state when electric power is being supplied from the power  
supply equipment to the movable body equipment even though the movable  
body equipment should refuse power reception from the power supply  
equipment.

[CLAIM 2] The resonance type non-contact power supply system according to  
claim 1, wherein the control unit is configured to bring the matching  
unit into a mismatch state when a charging operation of the electrical  
storage device cannot be canceled even though cancellation of the  
charging operation is desired.

[CLAIM 3] The resonance type non-contact power supply system according to  
claim 1 or 2, wherein the case where electric power is being supplied  
even though power reception should be refused is a case where the  
charging operation of the electrical storage device is not completed even  
though a charging-completion signal associated with the full charge state  
of the electrical storage device has been output.

[CLAIM 4] The resonance type non-contact power supply system  
according to any one of claims 1 to 3, wherein the movable body equipment  
is mounted and used in an electric vehicle.

[CLAIM 5] The resonance type non-contact power supply system according to  
any one of claims 1 to 4, wherein the power supply equipment includes a  
reflected electric power detector, which detects reflected electric power  
from the movable body equipment to the power supply equipment, and the  
power supply equipment is configured to stop power supply if a state in  
which the reflected electric power is not less than a preset value  
continues for a set period of time or longer.

[CLAIM 6] The resonance type non-contact power supply system according to  
any one of claims 1 to 5, wherein the control unit is configured to  
adjust the matching unit on the basis of data indicative of a  
relationship between a state of charge of the electrical storage device  
when the charging operation is carried out in a state in which the  
electrical storage device is normally charged and a suitable impedance of  
the matching unit corresponding to the state of charge.

2007 年以降の中国公開特許は公報レベルに  
全クレームが収録されている

## テキスト中の数値検索とは

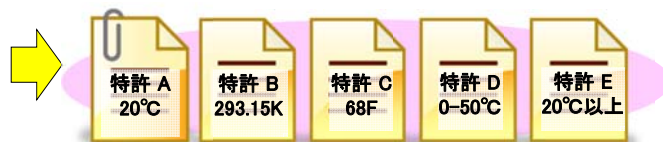
テキスト中の数値データと物性の種類をリンクさせて検索できる機能

特定の数値で検索

=> S 20 C/TEMP

数値範囲で検索

=> S 10-30 C/TEMP



さまざまな単位や数値範囲で表記された特許がヒット!

## 検索対象フィールド

発明レベル

\* ABDT, ABEX, ABEQ も検索対象に含まれる

公報レベル

公報レベルの情報も検索対象

## 検索できる数値の種類

全般	物質量, 面積, ビット, バイト, 温度, 質量, パーセント, コンダクタンス, 大きさ(長さ, 厚さなど), 時間, 体積
電気・光学 エネルギー	電力, 電気抵抗, 周波数, 電圧, 照度, 光束, 光度, 放射能, エネルギー
力学	力, 圧力, 表面張力, ばね定数
基本物性	モル濃度, 密度, 動的粘度, 動粘性率, 分子量, 水素イオン濃度
その他	角度, 磁界強度, 質量流量, 速度, 角速度

## 入力方法

=> S 数値 単位/数値検索フィールド

\* 単位を省略するとデフォルト単位で検索される

=> S 数値検索フィールド/PHP

\* その物性が数値で表記されているものをまとめて検索できる

## 入力例

=> S 60 C/TEMP

← 温度 60 °C の検索

=> S 50<=M

← 質量 50 kg 以上の検索

=> S 100-300/MFL

← 質量流量 100-300 kg/s の検索

=> S DOS/PHP

← 投与量の数値が記載されているものを検索

## 例 ガラス転移温度が 100-200 °C のポリアミドに関する特許

=> S (POLYAMIDE? OR POLY (W) AMIDE?)/BI, BIEX ← ポリアミドのキーワード  
L1 174451 (POLYAMIDE? OR POLY (W) AMIDE?)/BI, BIEX

=> S (GLASS (1A) TRANSIT? (1A) (TEMP? OR POINT) OR TG)/BI, BIEX  
L2 84369 (GLASS (1A) TRANSIT? (1A) (TEMP? OR POINT) OR TG)  
/BI, BIEX ↑ ガラス転移温度のキーワード

↓ 100-200 °Cの温度が記載されている

=> S L1 (P) L2 (3A) 100-200 C/TEMP  
L3 784 L1 (P) L2 (3A) 100-200 C/TEMP

キーワードと数値検索を掛け合わせることで目的の物性値に限定できる

=> D KWIC 13 46

L3 ANSWER 13 OF 784 WPINDEX COPYRIGHT 2015 THOMSON REUTERS on STN  
TECH . . .  
monocyclic cycloalkane diamine, bridge ring-type cycloalkane diamine, and  
diamine compound of formula (I).  
E=coupling group;  
Z=hydrocarbyl;  
R2=amino;and  
n=0 or more.  
POLYMERS - Preferred Properties: The polyamide resin has glass  
transition temperature of 165 degrees C or more. The refractive  
index of polyamide resin at 25 degrees C and wavelength of 589 nm is  
1.55 or more.

発明レベル (Technology Focus)  
でヒット

L3 ANSWER 46 OF 784 WPINDEX COPYRIGHT 2015 THOMSON REUTERS on STN  
Member . . .  
of crystallinity is less than 10%.  
[CLAIM 7] According to claim according to claim 1, 2 or 3 of said  
semi-aromatic polyamide, wherein a semi-aromatic polyamide of glass  
transition temperature is more than 130 degrees centigrade.  
[CLAIM 8] -a according to claim according to any one of claims 1-7 of a  
preparation method of semi-aromatic.

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## まとめ

- ・ WPI ファイルのレコードはトムソン・ロイター作成情報である**発明レベル**と公報由来の情報から成る**公報レベル**で構成されている
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## 参考資料

- ・ 「特許 II」講習会テキスト  
[http://www.jaici.or.jp/stn/pdf/text\\_pat2.pdf](http://www.jaici.or.jp/stn/pdf/text_pat2.pdf)
- ・ アジア・ブラジルの特許収録状況 (2014.5)  
<http://www.jaici.or.jp/stn/pdf/asiapat.pdf>